Product data sheet

1. General description

Planar passivated high commutation three quadrant triac in a SOT186A "full pack" plastic package. This triac is intended for use in motor control circuits where very high blocking voltage, high static and dynamic dV/dt as well as high dlcom/dt can occur. This "series C0T" triac will commutate the full RMS current at the maximum rated junction temperature ($T_{j(max)} = 150 \, ^{\circ}\text{C}$) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

2. Features and benefits

- · High minimum IGT for guaranteed immunity to gate noise
- Full cycle AC conduction
- High junction operating temperature capability (T_{j(max)} = 150 °C)
- Over-voltage withstand capability to IEC 61000-4-5
- · Pin compatible with standard triacs
- · Planar passivated for voltage ruggedness and reliability
- · Protective self turn-on capability for high energy transients
- · Less sensitive gate for high noise immunity
- Triggering in three quadrants only
- Very high immunity to false turn-on by dV/dt and IEC 61000-4-4 fast transient
- Package meets UL94V0 flammability requirement
- · Package is RoHS compliant
- Package meets UL1557 isolation test requirement rated at 2500V RMS

3. Applications

- AC fan, pump and compressor controls
- Highly inductive, resistive and safety loads
- Large and small appliances (White Goods)
- · Reversing induction motor controls e.g. vertical axis washing machines
- Applications subject to high temperature (T_{i(max)} = 150 °C)

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit						
Absolute	Absolute maximum rating									
V_{DRM}	repetitive peak off-state voltage		1000	V						
I _{T(RMS)}	RMS on-state current	full sine wave; T _h ≤ 105 °C; Fig. 1; Fig. 2; Fig. 3	8	А						
I _{TSM}	non-repetitive peak on- state current	full sine wave; t_p = 20 ms; $T_{j(init)}$ = 25 °C; Fig. 4; Fig. 5	100	А						
		full sine wave; t_p = 16.7 ms; $T_{j(init)}$ = 25 °C	110	Α						
T _j	junction temperature		150	°C						

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G + T_j = 25 \text{ °C; } Fig. 7$	5	-	35	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-$ $T_j = 25 \text{ °C; } Fig. 7$	5	-	35	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-} $ $T_j = 25 \text{ °C; } Fig. 7$	5	-	35	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	40	mA
V _T	on-state voltage	I _T = 10 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.21	1.6	V
Dynamic	characteristics		'			
dV _D /dt	rate of rise of off-state voltage	Total Control		-	-	V/µs
		V_{DM} = 670 V; T_j = 150 °C; $(V_{DM}$ = 67% of V_{DRM}); exponential waveform; gate open circuit	1000	-	-	V/µs
dI _{com} /dt	rate of change of commutating current	$V_D = 400 \text{ V}; T_j = 150 \text{ °C}; I_{T(RMS)} = 8 \text{ A};$ $dV_{com}/dt = 20 \text{ V/}\mu\text{s}; \text{ gate open circuit};$ snubberless condition	12	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 150 \text{ °C}; I_{T(RMS)} = 8 \text{ A};$ $dV_{com}/dt = 10 \text{ V/}\mu\text{s}; \text{ gate open circuit}$	15	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 150 \text{ °C}; I_{T(RMS)} = 8 \text{ A};$ $dV_{com}/dt = 1 \text{ V/}\mu\text{s}; \text{ gate open circuit}$	20	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	mb	T2—T1
2	T2	main terminal 2		sym051
3	G	gate		Symoon
mb	n.c.	mounting base; isolated		
			1 2 3	

6. Ordering information

Table 3. Ordering information

Type number	Package	Package				
	Name	Description	Version			
BTA408X-1000C0T	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"	SOT186A			

7. Marking

Table 4. Marking codes

Type number	Marking codes
BTA408X-1000C0T	BTA408X-1000C0T

BTA408X-1000C0T

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8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit	
V_{DRM}	repetitive peak off-state voltage		1000	V	
I _{T(RMS)}	RMS on-state current	full sine wave; $T_h \le 105^{\circ}C$; Fig. 1; Fig. 2; Fig. 3	8	А	
I _{TSM} non-repetitive peak on- state current		full sine wave; t_p = 20 ms; $T_{j(init)}$ = 25 °C; Fig. 4; Fig. 5	100	А	
		full sine wave; t_p = 16.7 ms; $T_{j(init)}$ = 25 °C	110	А	
l ² t	I ² t for fusing	t _p = 10ms; sine wave	50	A ² s	
dl _⊤ /dt	rate of rise of on-state current	I _G = 70mA	100	A/µs	
I _{GM}	peak gate current		2	А	
P_{GM}	peak gate power		5	W	
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W	
T _{stg}	storage temperature		-40 to 150	°C	
T _j	junction temperature		150	°C	
V _{pp} peak pulse voltage		peak pulse voltage T _j = 25 °C; non-repetitive, off-state; ten pulses on each voltage polarity; 20s or more between successive pulses			

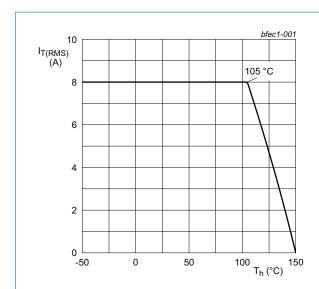
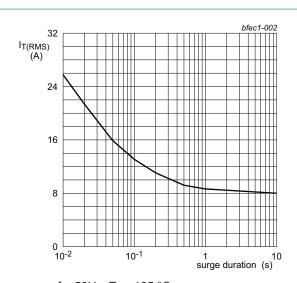


Fig. 1. RMS on-state current as a function of heatsink temperature; maximum values



f = 50Hz; T_h = 105 °C Fig. 2. RMS on-state current as a function of surge duration; maximum values

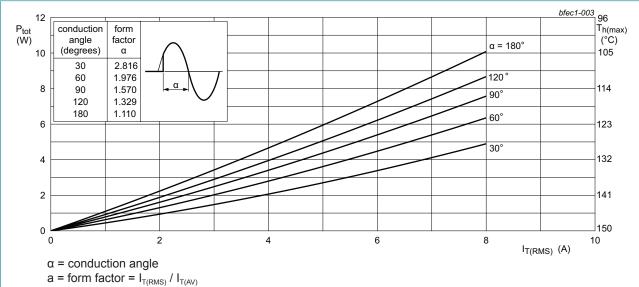


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

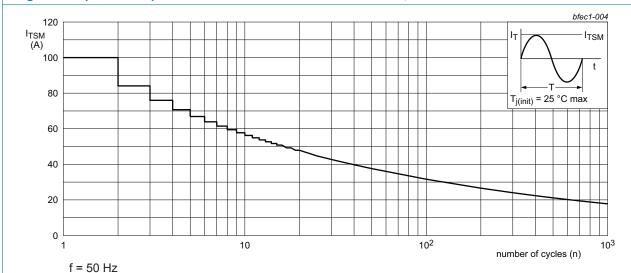
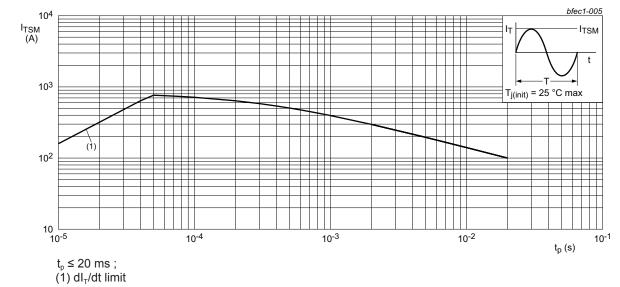


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

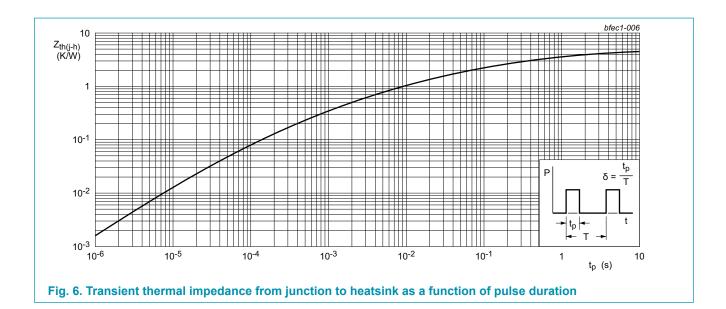


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9. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{\text{th(j-h)}}$	thermal resistance from junction to heatsink	with heatsink compound; Fig. 6	-	-	4.5	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W



10. Isolation characteristics

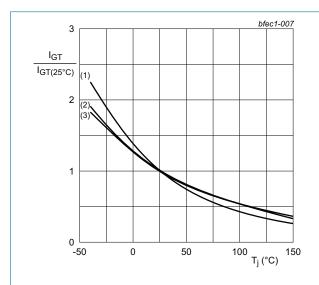
Table 6. Isolation characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{isol(RMS)}	RMS isolation voltage	50 Hz \leq f \leq 60 Hz; RH \leq 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
C _{isol}	isolation capacitance	from cathode to external heatsink	-	10	-	PF

11. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					'
I _{GT}	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G+;$ $T_j = 25 \text{ °C; } Fig. 7$	5	-	35	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + \text{ G-;} $ $T_j = 25 \text{ °C; } \underline{\text{Fig. 7}}$	5	-	35	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2- \text{ G-;}$ $T_j = 25 \text{ °C; } \frac{\text{Fig. 7}}{}$	5	-	35	mA
L	latching current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2+ \text{ G+;} $ $T_j = 25 \text{ °C; } \underline{\text{Fig. 8}}$	-	-	50	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-;$ $T_j = 25 \text{ °C; } Fig. 8$	-	-	70	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-;}$ $T_j = 25 \text{ °C; } \underline{\text{Fig. 8}}$	-	-	50	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	40	mA
V _T	on-state voltage	$I_T = 10 \text{ A}; T_j = 25 \text{ °C}; Fig. 10$		1.21	1.6	V
V_{GT}	gate trigger voltage	e $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$ Fig. 11		0.7	1	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 150 \text{ °C};$ Fig. 11	0.25	0.4	-	V
I _D	off-state current	V _D = 1000 V; T _j = 25 °C	-	-	10	μA
		V _D = 1000 V; T _j = 150 °C	-	0.4	2	mA
Dynamic o	haracteristics		,			
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 670 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	1500	-	-	V/µs
		V_{DM} = 670 V; T_{j} = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	1000	-	-	V/µs
dI _{com} /dt	rate of change of commutating current	$V_D = 400 \text{ V; } T_j = 150 ^{\circ}\text{C; } I_{T(RMS)} = 8 \text{ A;}$ $dV_{com}/dt = 20 V/\mu\text{s; gate open circuit;}$ snubberless condition	12	-	-	A/ms
		$V_D = 400 \text{ V; } T_j = 150 \text{ °C; } I_{T(RMS)} = 8 \text{ A;}$ $dV_{com}/dt = 10 \text{ V/}\mu\text{s; gate open circuit}$	15	-	-	A/ms
		$V_D = 400 \text{ V; } T_j = 150 \text{ °C; } I_{T(RMS)} = 8 \text{ A;}$ $dV_{com}/dt = 10 \text{ V/}\mu\text{s; gate open circuit}$	20	-	-	A/ms



(1) T2- G-(2) T2+ G-

(3) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

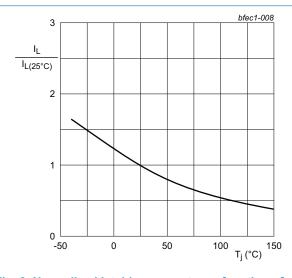


Fig. 8. Normalized latching current as a function of junction temperature

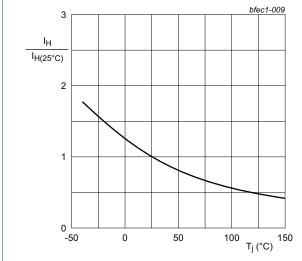
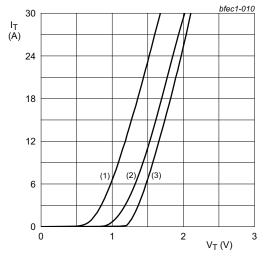


Fig. 9. Normalized holding current as a function of junction temperature



 $V_o = 1.188 \text{ V}; R_s = 0.0237 \Omega$

(1) $T_j = 150$ °C; typical values (2) $T_j = 150$ °C; maximum values

(3) $T_i = 25$ °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

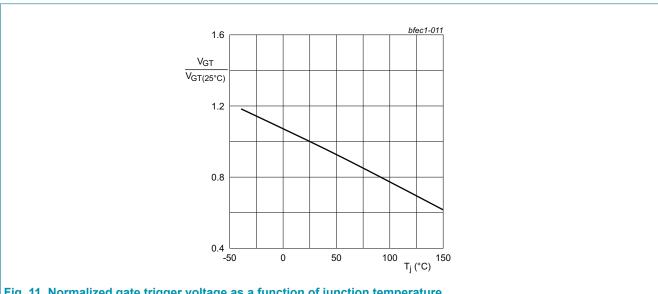
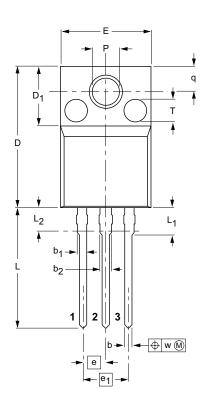


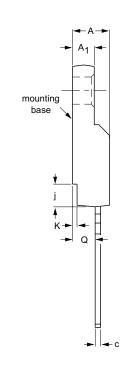
Fig. 11. Normalized gate trigger voltage as a function of junction temperature

12. Package outline

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 'full pack'

SOT186A





10 mm Luurunduurund scale

DIMENSIONS (mm are the original dimensions)

D		٠	are ar	o og.	iiai aiii		,														
UNIT	A	A ₁	b	b ₁	b ₂	С	D	D ₁	E	е	e ₁	j	к	L	L ₁	L ₂ ⁽¹⁾ max.	Р	Q	q	T ⁽²⁾	w
mm	4.6 4.0	2.9 2.5	0.9 0.7	1.1 0.9	1.4 1.0	0.7 0.4	15.8 15.2	6.5 6.3	10.3 9.7	2.54	5.08	2.7 1.7	0.6 0.4	14.4 13.5	3.30 2.79	3	3.2 3.0	2.6 2.3	3.0 2.6	2.5	0.4

Notes

- 1. Terminal dimensions within this zone are uncontrolled.
- 2. Both recesses are $\boxtimes 2.5 \times 0.8$ max. depth

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT186A		3-lead TO-220F			-02-04-09 06-02-14

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13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition		
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.		
Preliminary [short] data sheet Qualification		This document contains data from the preliminary specification.		
Product Production		This document contains the product specification.		

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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For more information, please visit: http://www.ween-semi.com For sales office addresses, please send an email to: salesaddresses@ween-semi.com Date of release: 12 July 2017

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